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Amendments to the Specification:

Please amend the top of page 1 as follows:

~~Method, Computer Program Product and Apparatus for Substrate Processing~~ Method, Computer Program Product and Apparatus for Scheduling Maintenance Actions in a Substrate Processing System

Please amend paragraph [0046] on page 11 as follows:

[0046] In Figure 3b, an example of a gap in the flow of substrates caused by maintenance action in the lithographic apparatus 5 is shown affecting the flow of substrates through the substrate processing system. In this example, the lithographic apparatus 5 is taken down for routine maintenance. As can be seen, the substrates entering the lithographic apparatus 5 are stopped (as represented by the dark shaded substrates) while the existing substrates in the substrate processing system continue to flow through the substrate processing system (as represented by the light shaded substrates). In an uncommon circumstance, all the substrates may stop in the substrate processing system. Due to the lithographic apparatus maintenance, a gap between substrates 23 and 34 is created which reduces the productivity of the substrate processing system.

Please amend paragraph [0056] on pages 14-15 as follows:

[0056] For example, referring to Figure 3a, a maintenance action with respect to the coaters 12 causes a gap in the flow of substrates into the coaters 12. By checking the SEMI interface, the time and location of the gap between substrates at the coaters can be identified. The processing unit 17 (or a processing unit of the lithographic apparatus 5 and/or track 10) can determine or monitor when the gap in the processing of substrates reaches a part of the substrate processing system where another maintenance action can be performed. So, knowing when a substrate that just passed the point of occurrence of the gap, i.e. the coaters, will reach another part of the substrate processing system, e.g., the exit of the lithographic apparatus 5, a maintenance can be scheduled for and performed when that substrate reaches, is in or leaves that other part of the substrate processing system.

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Please amend the top of page 28 as follows:

~~Method, Computer Program Product and Apparatus for Substrate Processing~~ <u>Method, Computer Program Product and Apparatus for Scheduling Maintenance Actions in a Substrate Processing System</u>

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